VISHAY MAS
GENERAL SEMICONDUCTOR

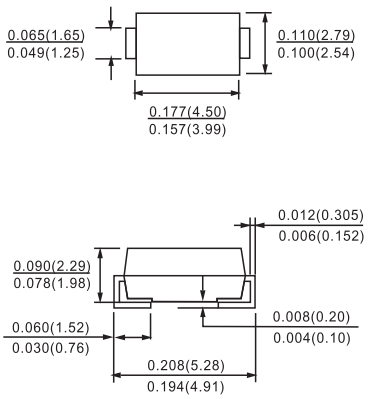
ER1A THRU ER1J

50V-600V 1.0A

FEATURES

- For surface mounted applications
- Low profile package
- Built-in strain relief
- Easy pick and place
- Superfast recovery times for high efficiency
- Plastic package has Underwriters Laboratory Flammability Classification 94V-O
- Glass passivated junction
- High temperature soldering: 260 ¢J/10 seconds at terminals

DO-214AC(SMA)



Dimensions in inches and (millimeters)

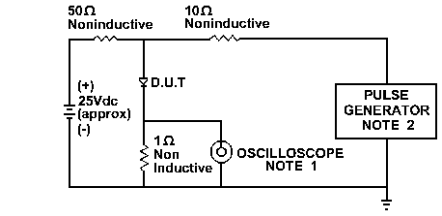
MECHANICAL DATA

Case: JEDEC DO-214AC molded plastic
Terminals: Solder plated, solderable per MIL-STD-750, Method 2026
Polarity: Indicated by cathode band
Standard packaging: 12mm tape (EIA-481)
Weight: 0.003 ounce, 0.093 gram

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Characteristic	Symbol	ER1A	ER1B	ER1C	ER1D	ER1E	ER1G	ER1J	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RRM} V_{RWM} V_R	50	100	150	200	300	400	600	V
RMS Reverse Voltage	$V_{R(RMS)}$	35	70	105	140	210	280	420	V
Average Rectified Output Current @T_L = 100°C	I_O	1.0							A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	30							A
Forward Voltage @I_F = 1.0A	V_{FM}	0.95				1.25		1.7	V
Peak Reverse Current @T_A = 25°C At Rated DC Blocking Voltage @T_A = 100°C	I_{RM}	5.0 500							μA
Reverse Recovery Time (Note 1)	t_{rr}	35							nS
Typical Junction Capacitance (Note 2)	C_j	10							pF
Typical Thermal Resistance (Note 3)	$R_{\theta JL}$	34							K/W
Operating and Storage Temperature Range	T_j, T_{STG}	-65 to +150							°C

Note: 1. Measured with I_F = 0.5A, I_R = 1.0A, I_{rr} = 0.25A,
2. Measured at 1.0 MHz and applied reverse voltage of 4.0 V DC.
3. Mounted on P.C. Board with 8.0mm^2 land area.



NOTE:1.Rise Time = 7ns max.
Input Impedance = 1 megohm. 22pF
2.Rise Time = 10ns max.
Source Impedance = 50 Ohms

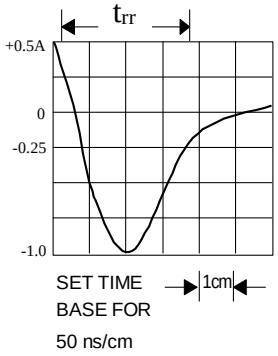


Fig. 1-REVERSE RECOVERY TIME CHARACTERISTIC AND TEST CIRCUIT DIAGRAM

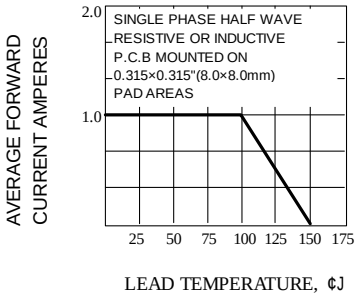


Fig. 2-MAXIMUM AVERAGE FORWARD CURRENT RATING

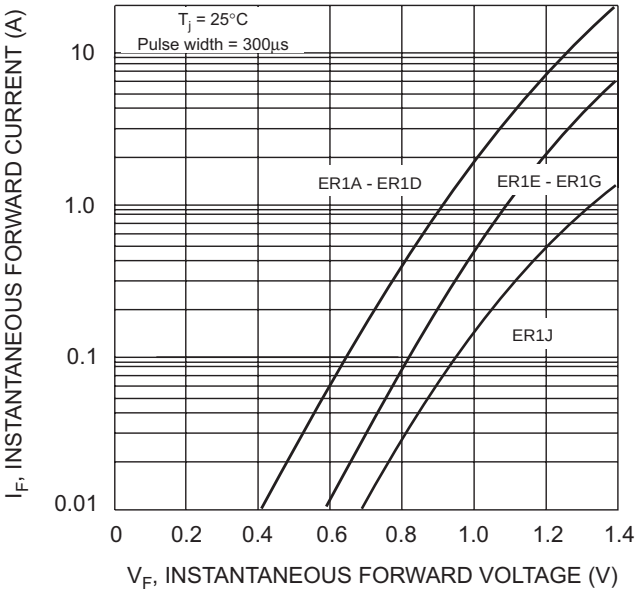


Fig.3 Typical Forward Characteristics

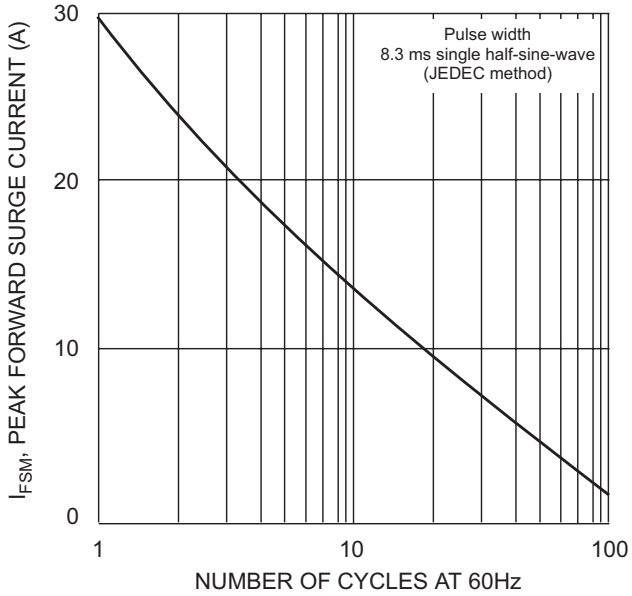


Fig.4 PEA FORWARD SURGE CURRENT

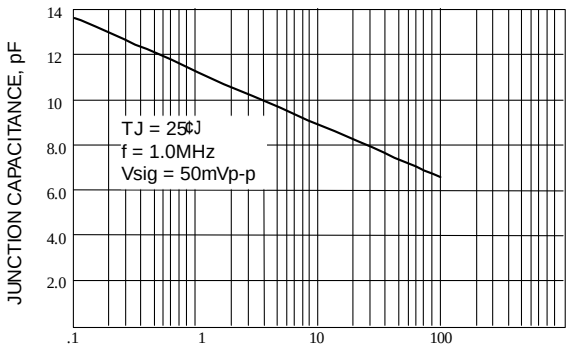


Fig. 5-TYPICAL JUNCTION CAPACITANCE